

Germany-Ingolstadt: Microelectronic machinery and apparatus
OJ S 216/2019 08/11/2019
Contract award notice
Supplies

Legal Basis:

Directive 2014/24/EU

Section I: Contracting authority

I.1. Name and addresses

Official name: Technische Hochschule Ingolstadt

Postal address: Esplanade 10

Town: Ingolstadt

NUTS code: DE211 Ingolstadt, Kreisfreie Stadt

Postal code: 85049

Country: Germany

Contact person: Bhogaraju, Sri Krishna

E-mail: info@thi.de

Telephone: +49 84193480

Fax: +49 8419348200

Internet address(es):

Main address: <https://www.auftraege.bayern.de>

Address of the buyer profile: <https://www.thi.de>

I.2. Information about joint procurement

The contract is awarded by a central purchasing body

I.4. Type of the contracting authority

Other type: Technische Hochschule

I.5. Main activity

Education

Section II: Object

II.1. Scope of the procurement

II.1.1. Title

Bonder – Microelectronics packaging

Reference number: 2019000384

II.1.2. Main CPV code

31712100 Microelectronic machinery and apparatus

II.1.3. Type of contract

Supplies

II.1.4. Short description

As part of the IQLED project, Technische Hochschule Ingolstadt (THI) would like to procure an advanced bonder for the research lab „Microelectronics packaging“.

Im Rahmen des IQLED-Projekts möchte die Technische Hochschule Ingolstadt (THI) einen Advanced Bonder für das Forschungslabor „Microelectronics Packaging“ beschaffen.

II.1.6. Information about lots

This contract is divided into lots: no

II.1.7. Total value of the procurement

Value excluding VAT: 219 990,01 EUR

II.2. Description

II.2.3. Place of performance

NUTS code: DE211 Ingolstadt, Kreisfreie Stadt

II.2.4. Description of the procurement

As part of the IQLED project, Technische Hochschule Ingolstadt (THI), would like to procure an advanced bonder for reasearch lab „Microelectronics packaging“.

Im Rahmen des IQLED Projektes möchte die THI einen Advanced Bonder für das Forschungslabor „Microelectronics Packaging“ beschaffen.

II.2.5. Award criteria

Quality criterion - Name: Leistungskriteriea / Weighting: 50

Price - Weighting: 50

II.2.11. Information about options

Options: no

II.2.13. Information about European Union funds

The procurement is related to a project and/or programme financed by European Union funds:
no

II.2.14. Additional information

Section IV: Procedure

IV.1. Description

IV.1.1. Type of procedure

Open procedure

IV.1.3. Information about a framework agreement or a dynamic purchasing system

IV.1.8. Information about the Government Procurement Agreement (GPA)

The procurement is covered by the Government Procurement Agreement: yes

IV.2. Administrative information

IV.2.1. Previous publication concerning this procedure

Notice number in the OJ S: [2019/S 176-428108](#)

IV.2.8. Information about termination of dynamic purchasing system

IV.2.9. Information about termination of call for competition in the form of a prior information notice

Section V: Award of contract

Title:

Bonder – Microelectronics packaging

A contract/lot is awarded: yes

V.2. Award of contract**V.2.1. Date of conclusion of the contract**

28/10/2019

V.2.2. Information about tenders

Number of tenders received: 3

The contract has been awarded to a group of economic operators: no

V.2.3. Name and address of the contractor

Official name: Finetech GmbH&Co.KG

Town: Berlin

NUTS code: 00 Other or Not Specified

Country: Germany

The contractor is an SME: no

V.2.4. Information on value of the contract/lot

Total value of the contract/lot: 219 990,01 EUR

V.2.5. Information about subcontracting**Section VI: Complementary information**

VI.3. Additional information**VI.4. Procedures for review****VI.4.1. Review body**

Official name: Regierung von Oberbayern – Vergabekammer Südbayern

Postal address: Maximilianstr. 39

Town: München

Postal code: 80538

Country: Germany

E-mail: vergabekammer.suedbayern@reg-ob.bayern.de

Telephone: +49 8921762411

Fax: +49 8921762847

VI.5. Date of dispatch of this notice

04/11/2019